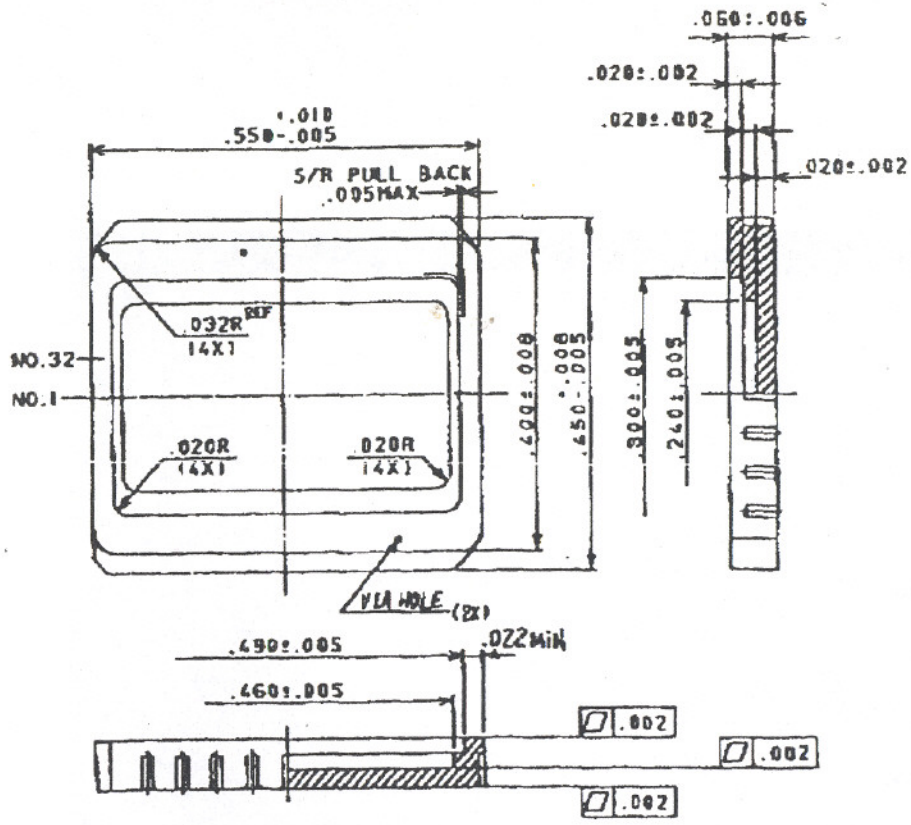
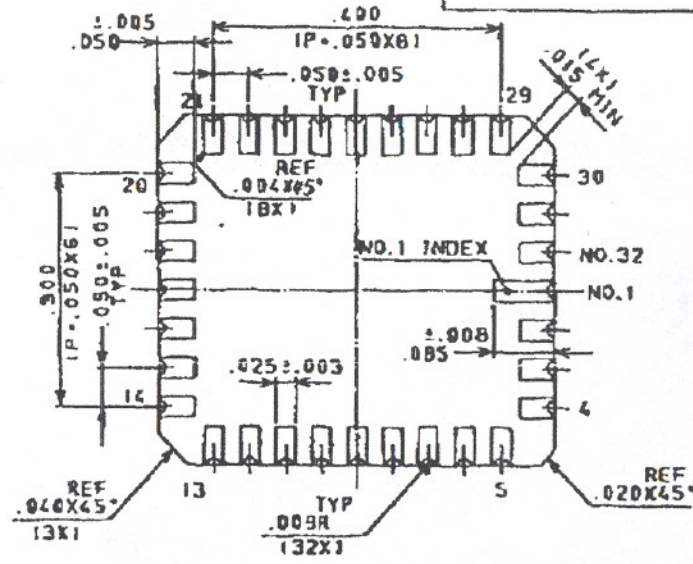
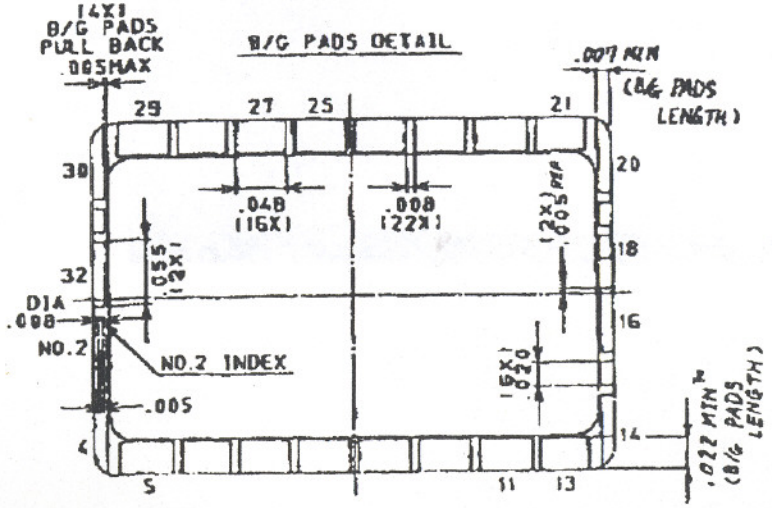
NTK TECHNICAL DIMENSIONS

LATEST REVISION'S DISCRIPTION







NOTES:

1. GOLD PLATE 80 μ INCHES MIN OVER 100 μ INCHES MIN NICKEL.
2. CONTACT PAD 1,12,17 AND 26 ARE NOT ELECTRICALLY CONNECTED TO ANY BONDING PAD.
3. NO LEAD TO BE ELECTRICALLY CONNECTED TO THE DIE ATTACH PAD. SEAL RING ISOLATED.

3				
2				
1	CERAMIC	BLACK ALUMINA	K.MAEDA NEW DRAWING	MAY.-1-199
Item	Name	Specification	Rev. Description	Date

NTK TECHNICAL CERAMICS
NOT SPARK PLUG CO., LTD

32 LD CHIP CARRIER

IRK32F1-5416A

MODIFIED DWG No.